



Product Change Notification

112548 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 112548 - 00
Change Title: Intel® NUC Kit DCCP847DY, Boxed
PCN 112548-00, Product Design
Change Bottom Cover and Capacitor
Date of Publication: August 29, 2013

Key Characteristics of the Change:

Product Design

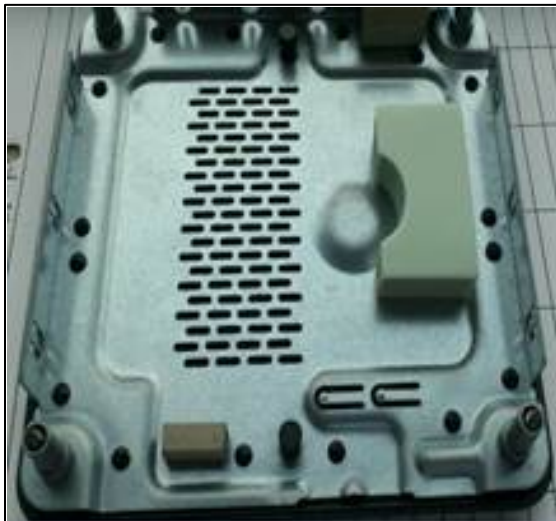
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Sep 19, 2013
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Description of Change to the Customer:

Intel will change the new bottom cover on the Intel® NUC Kit DCCP847DY to a 3.5mm thermal pad to enhance the thermal design (see images below).

Current Bottom Cover:



New Bottom Cover:



Additionally, capacitor C315 will change from 10u to 0.1u to enhance the RTC (Real Time Clock) circuit.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure there is no quality, reliability, or functional implication to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change SA	Pre Change AA	Post Change SA	Post Change AA
BOXDCCP847DYE	925743	G80888-104	G80890-103	G80888-105	G80890-104

PCN Revision History:

Date of Revision:

August 29, 2013

Revision Number:

00

Reason:

Originally Published PCN